

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

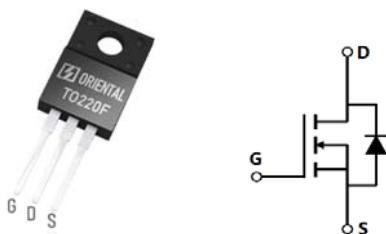
Key Performance Parameters

| Parameter | Value | Unit |
|-----------------------------------|-------|------|
| V_{DS} , min @ $T_{j(max)}$ | 600 | V |
| I_D , pulse | 24 | A |
| $R_{DS(ON)}$, max @ $V_{GS}=10V$ | 580 | mΩ |
| Q_g | 8.7 | nC |

Marking Information

| Product Name | Package | Marking |
|--------------|---------|------------|
| OSG55R580FF | TO220F | OSG55R580F |

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Value | Unit |
|---|-----------------------|------------|------|
| Drain-source voltage | V_{DS} | 550 | V |
| Gate-source voltage | V_{GS} | ± 30 | V |
| Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$ | I_D | 8 | A |
| Continuous drain current ¹⁾ , $T_c=100^\circ\text{C}$ | | 5 | |
| Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$ | $I_{D, \text{pulse}}$ | 24 | A |
| Continuous diode forward current ¹⁾ , $T_c=25^\circ\text{C}$ | I_S | 8 | A |
| Diode pulsed current ²⁾ , $T_c=25^\circ\text{C}$ | $I_{S, \text{pulse}}$ | 24 | A |
| Power dissipation ³⁾ , $T_c=25^\circ\text{C}$ | P_D | 26 | W |
| Single pulsed avalanche energy ⁵⁾ | E_{AS} | 130 | mJ |
| MOSFET dv/dt ruggedness, $V_{DS}=0\ldots 480\text{ V}$ | dv/dt | 50 | V/ns |
| Reverse diode dv/dt, $V_{DS}=0\ldots 480\text{ V}$, $I_{SD} \leq I_D$ | dv/dt | 15 | V/ns |
| Operation and storage temperature | T_{stg}, T_j | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal resistance, junction-case | $R_{\theta JC}$ | 4.8 | °C/W |
| Thermal resistance, junction-ambient ⁴⁾ | $R_{\theta JA}$ | 62.5 | °C/W |

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------------------|---------------------|------|------|------|---------------|---|
| Drain-source breakdown voltage | BV_{DSS} | 550 | | | V | $V_{GS}=0\text{ V}$, $I_D=250\text{ uA}$ |
| | | 600 | | | | $V_{GS}=0\text{ V}$, $I_D=250\text{ uA}$, $T_j=150^\circ\text{C}$ |
| Gate threshold voltage | $V_{GS(\text{th})}$ | 2.0 | | 4.0 | V | $V_{DS}=V_{GS}$, $I_D=250\text{ uA}$ |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ | | 0.5 | 0.58 | Ω | $V_{GS}=10\text{ V}$, $I_D=4\text{ A}$ |
| | | | 1.17 | | | $V_{GS}=10\text{ V}$, $I_D=4\text{ A}$, $T_j=150^\circ\text{C}$ |
| Gate-source leakage current | I_{GS} | | | 100 | nA | $V_{GS}=30\text{ V}$ |
| | | | | -100 | | $V_{GS}=-30\text{ V}$ |
| Drain-source leakage current | I_{DSS} | | | 1 | μA | $V_{DS}=550\text{ V}$, $V_{GS}=0\text{ V}$ |

Dynamic Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|------------------------------|---------------------|------|-------|------|------|---|
| Input capacitance | C _{iss} | | 357.6 | | pF | V _{GS} =0 V, V _{DS} =50 V, f=1 MHz |
| Output capacitance | C _{oss} | | 46.6 | | pF | |
| Reverse transfer capacitance | C _{rss} | | 1.73 | | pF | |
| Turn-on delay time | t _{d(on)} | | 17.3 | | ns | V _{GS} =10 V, V _{DS} =400 V, R _G =25 Ω, I _D =3.5 A |
| Rise time | t _r | | 8.4 | | ns | |
| Turn-off delay time | t _{d(off)} | | 28.9 | | ns | |
| Fall time | t _f | | 21.8 | | ns | |

Gate Charge Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|----------------------|----------------------|------|------|------|------|--|
| Total gate charge | Q _g | | 7.7 | | nC | V _{GS} =10 V, V _{DS} =400 V, I _D =3.5 A |
| Gate-source charge | Q _{gs} | | 1.8 | | nC | |
| Gate-drain charge | Q _{gd} | | 3.3 | | nC | |
| Gate plateau voltage | V _{plateau} | | 5.6 | | V | |

Body Diode Characteristics

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test condition |
|-------------------------------|------------------|------|-------|------|------|--|
| Diode forward voltage | V _{SD} | | | 1.3 | V | I _S =8 A, V _{GS} =0 V |
| Reverse recovery time | t _{rr} | | 165.9 | | ns | V _R =400 V, I _S =3.5 A, di/dt=100 A/μs |
| Reverse recovery charge | Q _{rr} | | 1.1 | | μC | |
| Peak reverse recovery current | I _{rrm} | | 12.6 | | A | |

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=100 V, V_{GS}=10 V, L=20 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

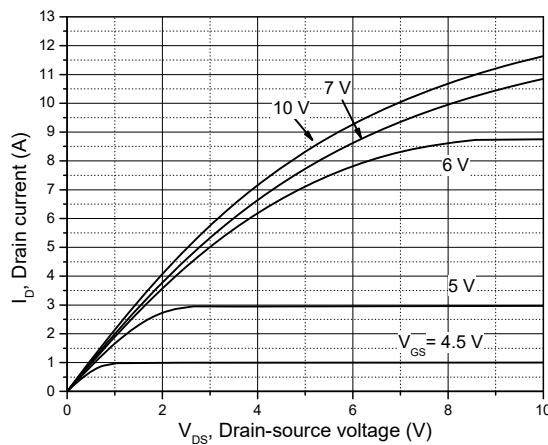


Figure 1. Typ. output characteristics

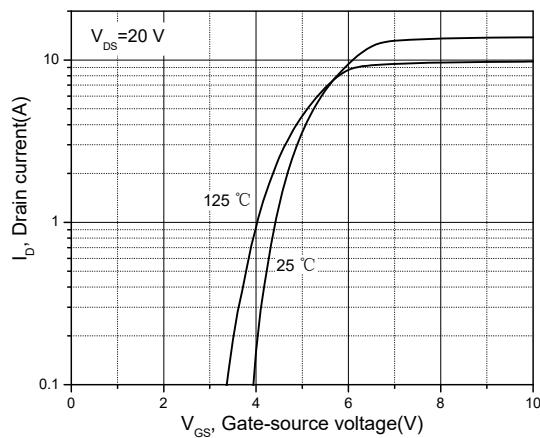


Figure 2. Typ. transfer characteristics

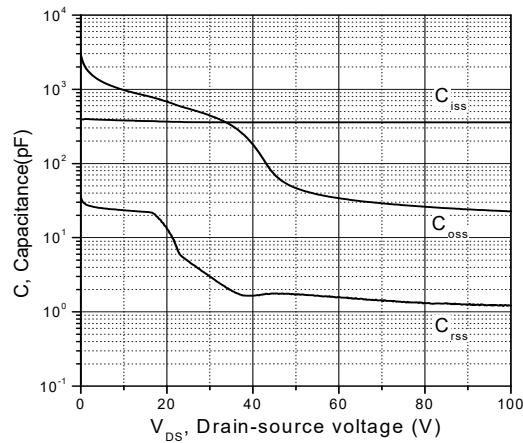


Figure 3. Typ. capacitances

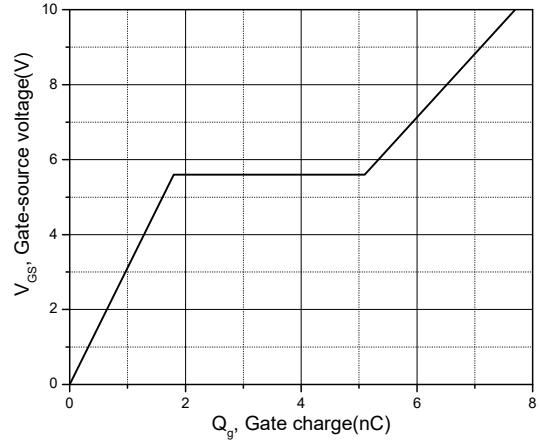


Figure 4. Typ. gate charge

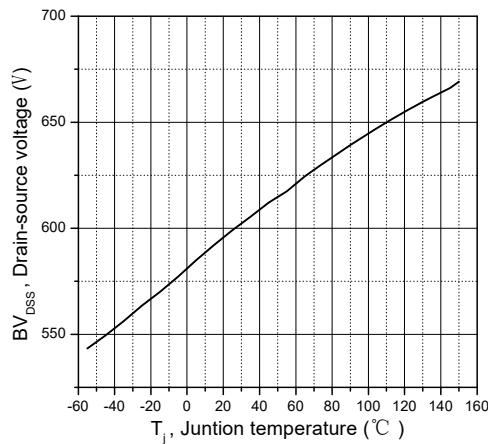


Figure 5. Drain-source breakdown voltage

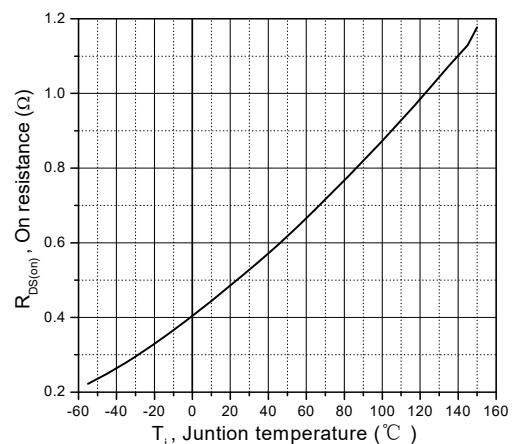
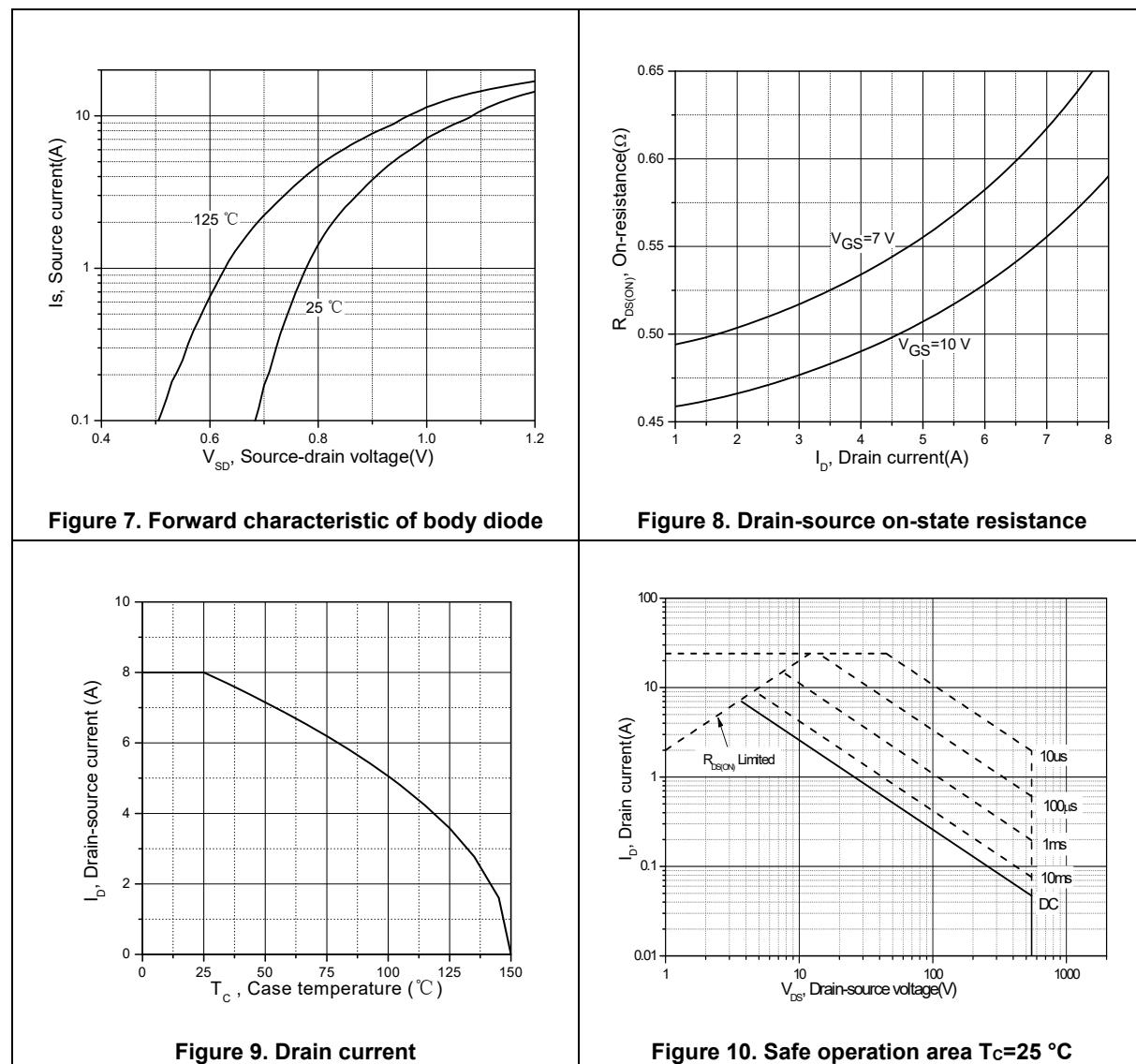
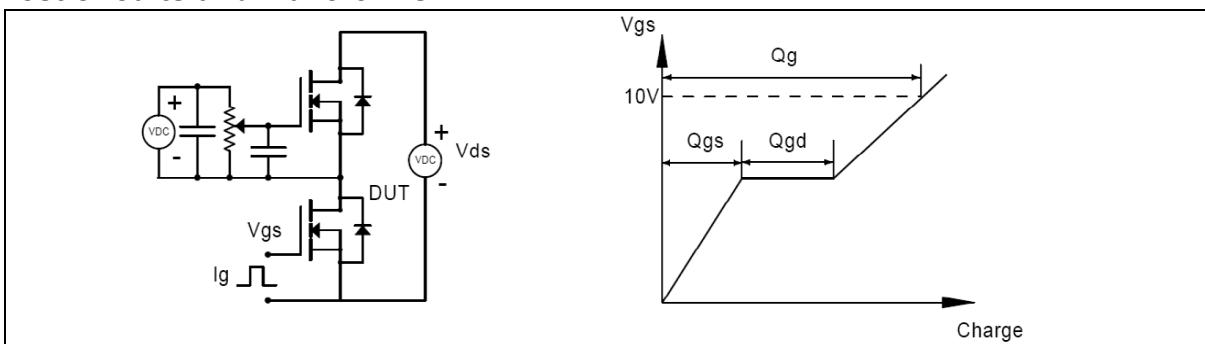
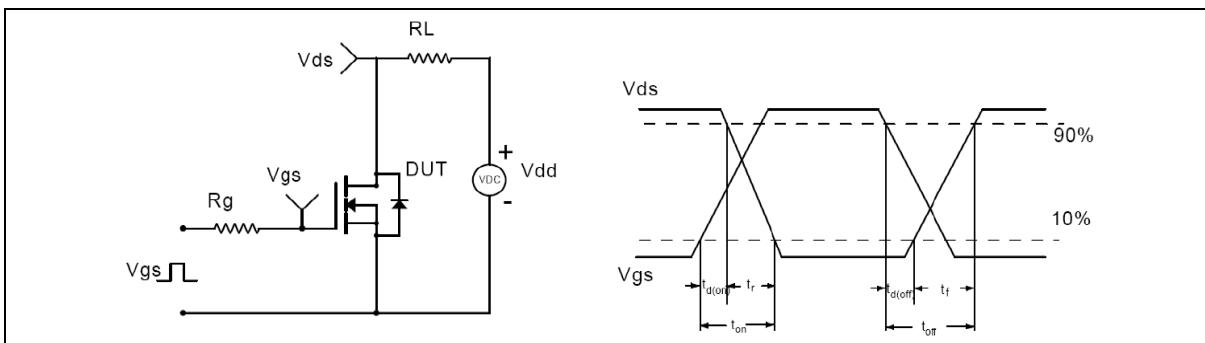
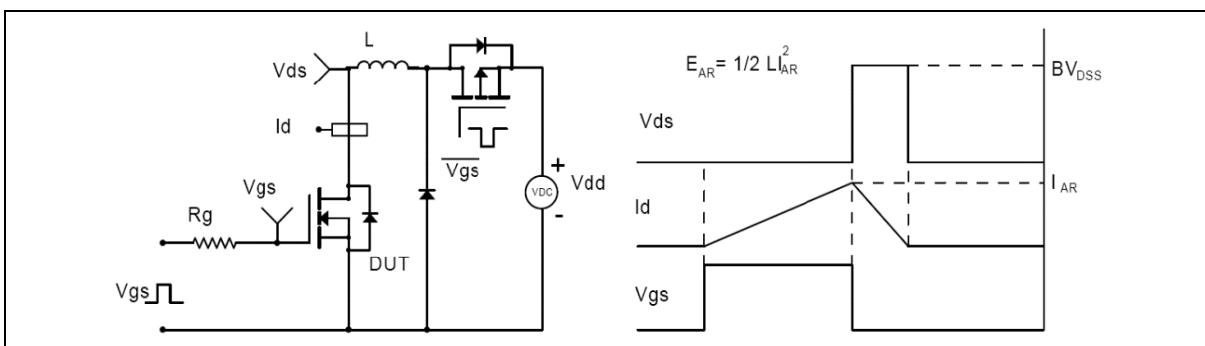
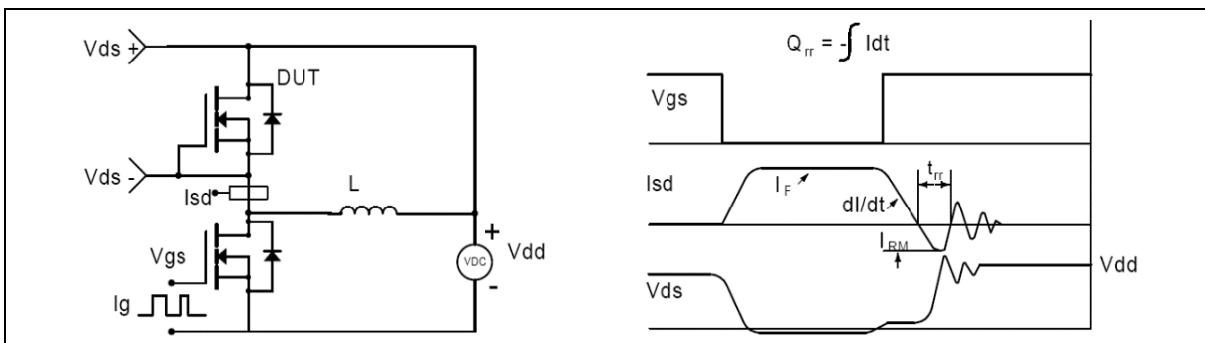
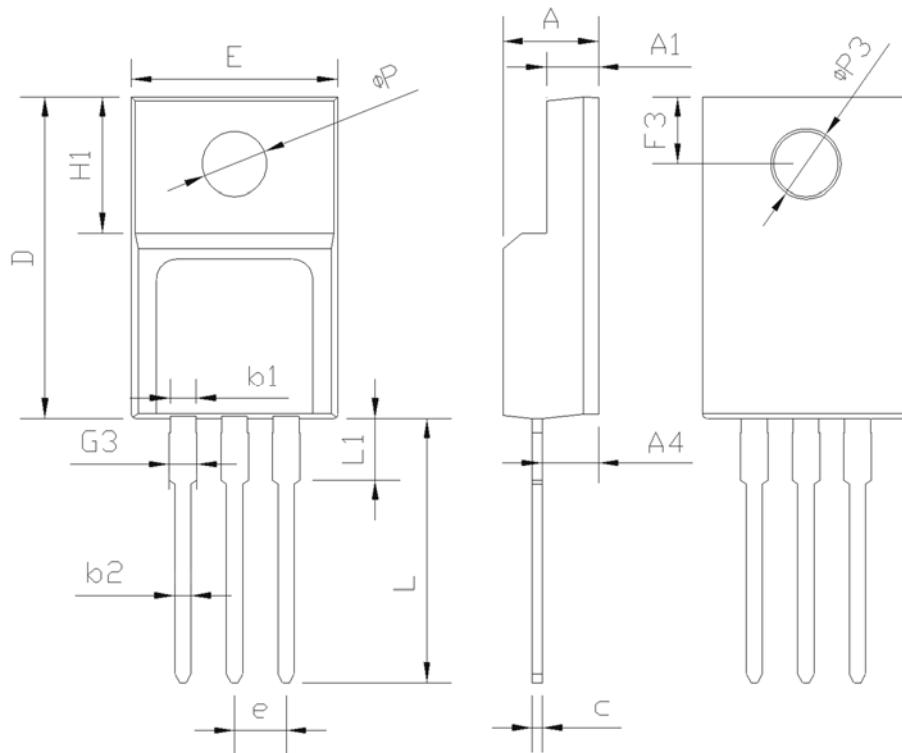


Figure 6. Drain-source on-state resistance



Test circuits and waveforms

Figure 1. Gate charge test circuit & waveform

Figure 2. Switching time test circuit & waveforms

Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

Figure 4. Diode reverse recovery test circuit & waveforms

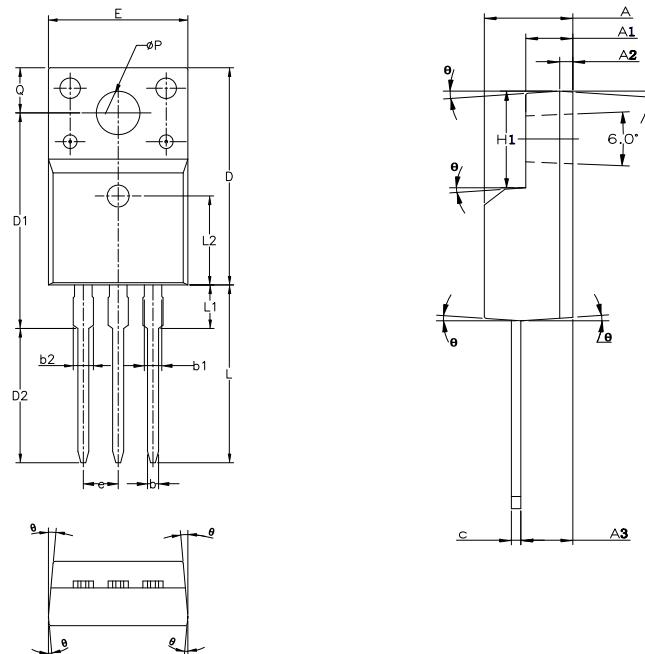
Package Information



| Symbol | mm | | |
|--------|----------|-------|-------|
| | Min | Nom | Max |
| E | 9.96 | 10.16 | 10.36 |
| A | 4.50 | 4.70 | 4.90 |
| A1 | 2.34 | 2.54 | 2.74 |
| A4 | 2.56 | 2.76 | 2.96 |
| c | 0.40 | 0.50 | 0.65 |
| D | 15.57 | 15.87 | 16.17 |
| H1 | 6.70 REF | | |
| e | 2.54 BSC | | |
| L | 12.68 | 12.98 | 13.28 |
| L1 | 2.88 | 3.03 | 3.18 |
| ΦP | 3.03 | 3.18 | 3.38 |
| ΦP3 | 3.15 | 3.45 | 3.65 |
| F3 | 3.15 | 3.30 | 3.45 |
| G3 | 1.25 | 1.35 | 1.55 |
| b1 | 1.18 | 1.28 | 1.43 |
| b2 | 0.70 | 0.80 | 0.95 |

Version 1: TO220F-C outline dimension

Package Information



| Symbol | mm | | |
|--------|----------|-------|-------|
| | Min | Nom | Max |
| A | 4.50 | 4.70 | 4.83 |
| A1 | 2.34 | 2.54 | 2.74 |
| A2 | 0.70 REF | | |
| A3 | 2.56 | 2.76 | 2.93 |
| b | 0.70 | - | 0.90 |
| b1 | 1.18 | - | 1.38 |
| b2 | - | - | 1.47 |
| c | 0.45 | 0.50 | 0.60 |
| D | 15.67 | 15.87 | 16.07 |
| D1 | 15.55 | 15.75 | 15.95 |
| D2 | 9.60 | 9.80 | 10.00 |
| E | 9.96 | 10.16 | 10.36 |
| e | 2.54 BSC | | |
| H1 | 6.48 | 6.68 | 6.88 |
| L | 12.68 | 12.98 | 13.28 |
| L1 | - | - | 3.50 |
| L2 | 6.50 REF | | |
| ΦP | 3.08 | 3.18 | 3.28 |
| Q | 3.20 | - | 3.40 |
| θ | 1° | 3° | 5° |

Version 2: TO220F-J outline dimension

Ordering Information

| Package Type | Units/ Tube | Tubes / Inner Box | Units/ Inner Box | Inner Boxes/ Carton Box | Units/ Carton Box |
|--------------|-------------|-------------------|------------------|-------------------------|-------------------|
| TO220F-C | 50 | 20 | 1000 | 6 | 6000 |
| TO220F-J | 50 | 20 | 1000 | 5 | 5000 |

Product Information

| Product | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| OSG55R580FF | TO220F | yes | yes | yes |

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